<table>
<thead>
<tr>
<th>Item</th>
<th>Qty</th>
<th>Reference</th>
<th>Value</th>
<th>Part Description</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Alternate Part</th>
<th>PCB Footprint</th>
<th>Note</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>5</td>
<td>C1 C2 C3 C4 C6</td>
<td>0.1 uF</td>
<td>CAP CER 0.1UF 10V 10% X7R 0402</td>
<td>Kemet</td>
<td>C0402C104K8RACTU</td>
<td>0402</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>1</td>
<td>C5</td>
<td>0.1 uF</td>
<td>CAP CER 0.1UF 25V 10% X7R 0603</td>
<td>Panasonic</td>
<td>ECJ-1VB10104K</td>
<td>0603</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>1</td>
<td>J1</td>
<td></td>
<td>CONN SOCKET FPC .4MM 80POS SMD</td>
<td>Panasonic</td>
<td>AXT580124</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>1</td>
<td>J2</td>
<td>50039-06001-001</td>
<td>CONN PLUG 60PIN-0.5MM</td>
<td>Aces</td>
<td>50039-06001-001</td>
<td></td>
<td>Made in Taiwan - Layout has to be modified when choosing a different connector</td>
<td></td>
</tr>
</tbody>
</table>
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